



SOT1570-5

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.50 mm pitch; 14 mm x 14 mm x 1.4 mm body

21 December 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-12-2021
Manufacturer package code	98ASA01602D

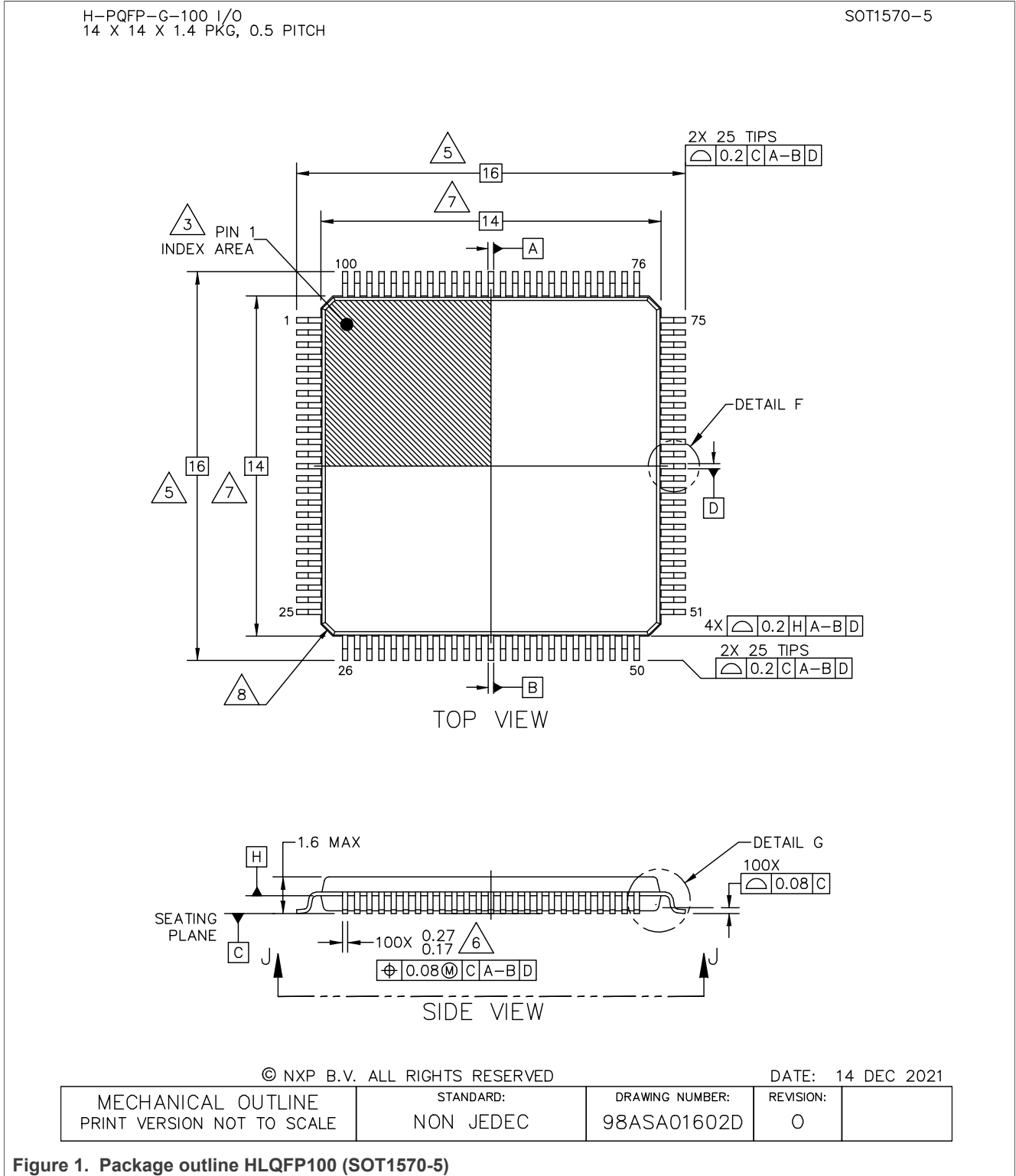
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
seated height	-	1.4	-	mm

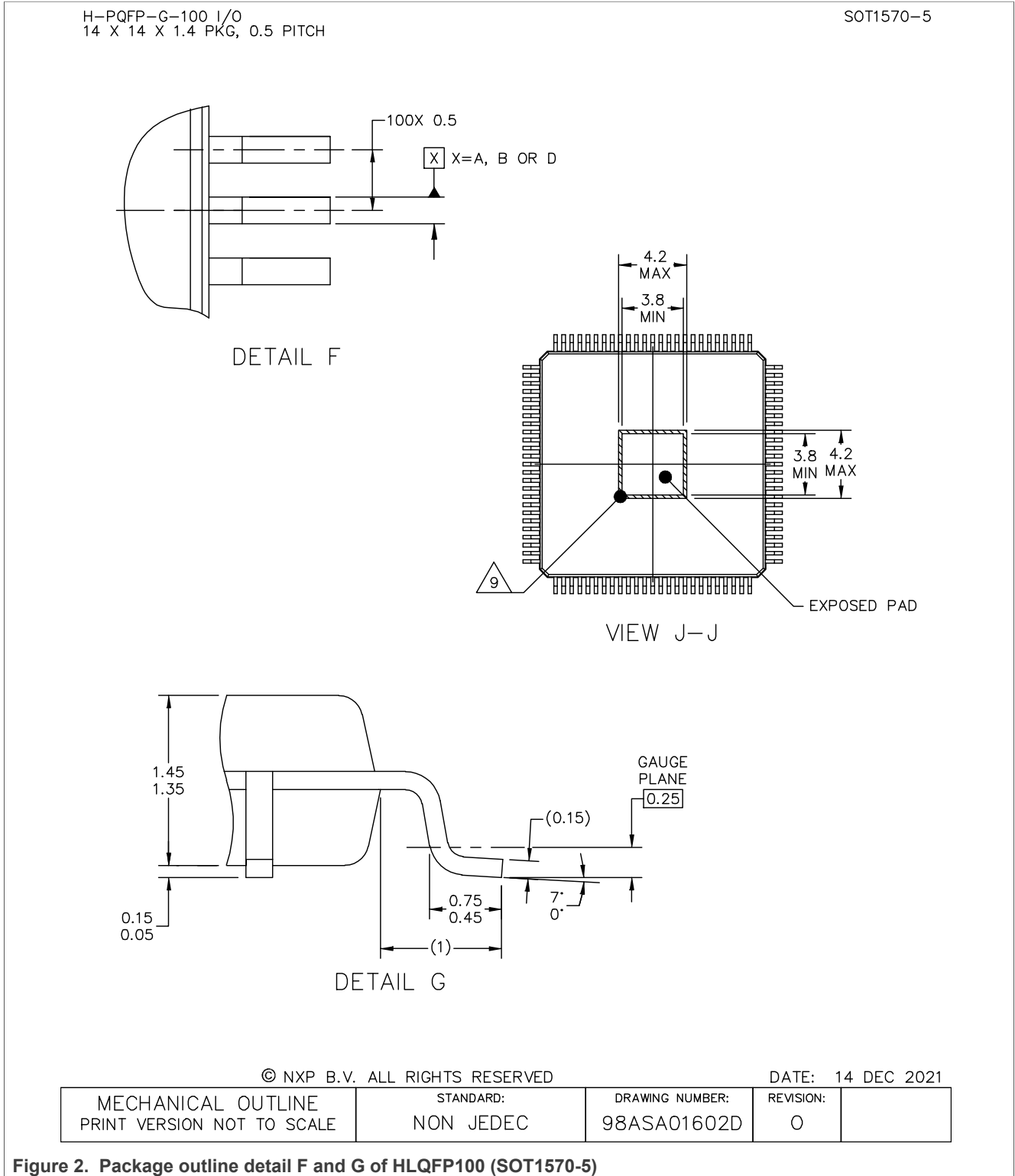


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2 Package outline

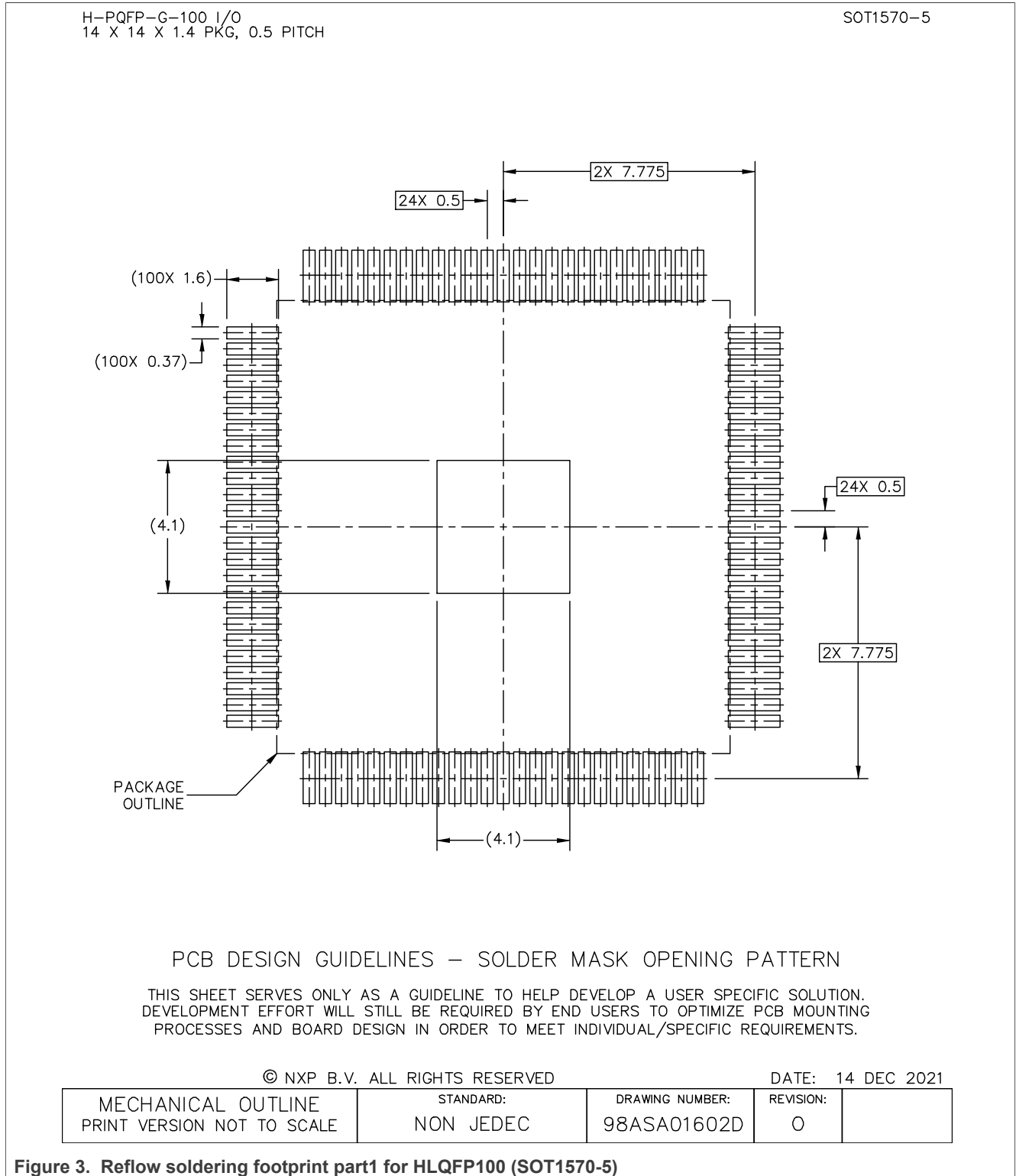


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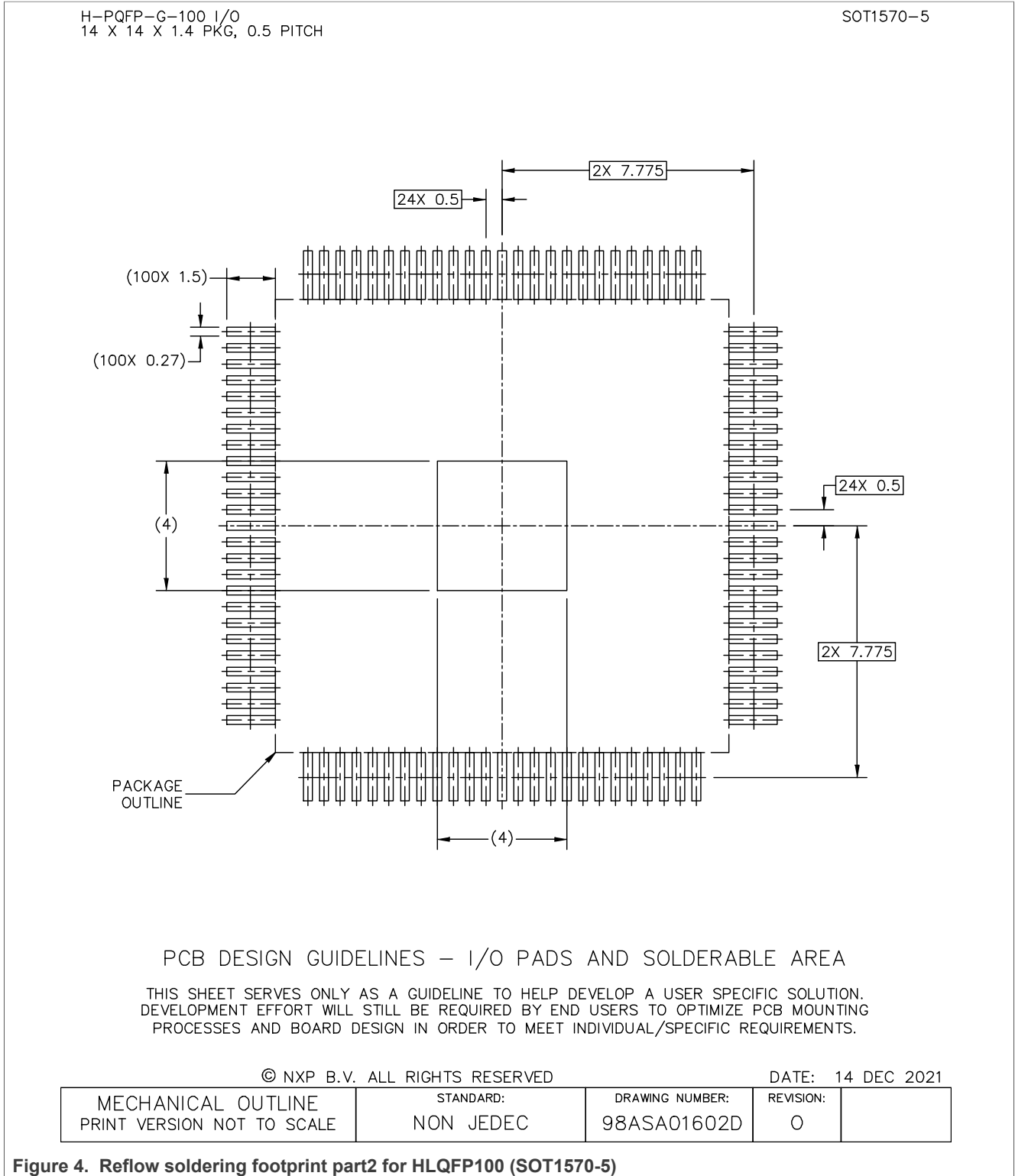


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3 Soldering



HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.50 mm pitch; 14 mm x 14 mm x 1.4 mm body



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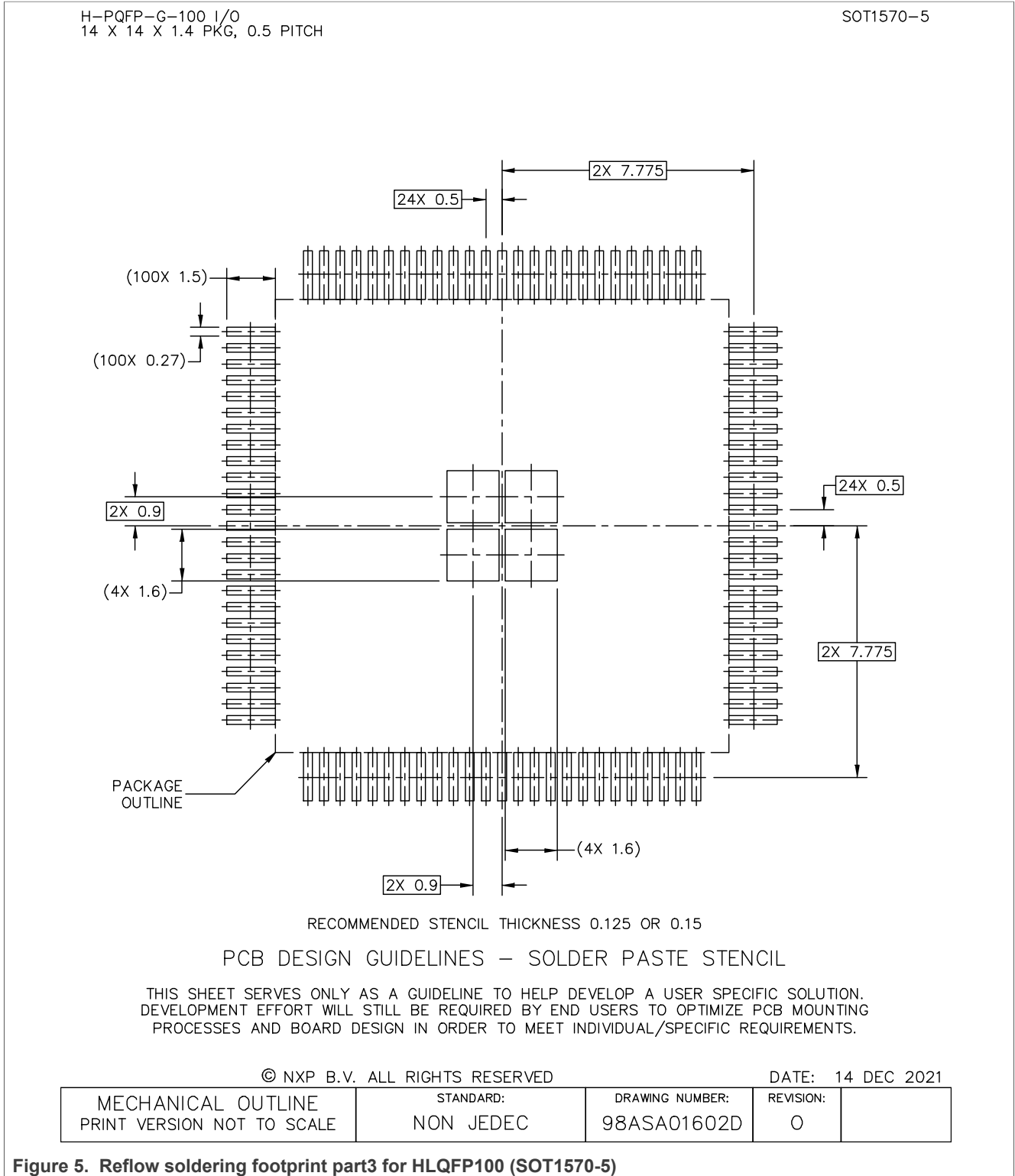


Figure 5. Reflow soldering footprint part3 for HLQFP100 (SOT1570-5)

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H-PQFP-G-100 I/O
14 X 14 X 1.4 PKG, 0.5 PITCH

SOT1570-5

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 14 DEC 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01602D	REVISION: 0	
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Figure 6. Package outline note HLQFP100 (SOT1570-5)

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4 Legal information

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